

1. General description

Planar passivated high commutation three quadrant triac in a SOT78 (TO-220AB) plastic package. This "series D" triac balances the requirements of commutation performance and gate sensitivity and is intended for interfacing with low power drivers including microcontrollers.

2. Features and benefits

- 3Q technology for improved noise immunity
- · Direct interfacing with low power drivers and microcontrollers
- Good immunity to false turn-on by dV/dt
- High commutation capability with very sensitive gate
- High voltage capability
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only
- Very sensitive gate for easy logic level triggering

3. Applications

- Electronic thermostats (heating and cooling)
- Motor controls e.g. washing machines and vacuum cleaners
- · Refrigeration and air-conditioner compressor controls

4. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{DRM}	repetitive peak off- state voltage		-	-	600	V
I _{T(RMS)}	RMS on-state current	full sine wave; T _{mb} ≤ 106 °C; <u>Fig. 1;</u> <u>Fig. 2; Fig. 3</u>	-	-	10	A
I _{TSM}	non-repetitive peak on- state current	full sine wave; T _{j(init)} = 25 °C; t _p = 20 ms; <u>Fig. 4</u> ; <u>Fig. 5</u>	-	-	85	A
		full sine wave; $T_{j(init)} = 25 \text{ °C};$ t _p = 16.7 ms	-	-	93	A
Tj	junction temperature		-	-	125	°C
Static chara	acteristics	· · · · · · · · · · · · · · · · · · ·				
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 7</u>	0.3	-	5	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _i = 25 °C; <u>Fig. 7</u>	0.3	-	5	mA

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 7</u>	0.3	-	5	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	10	mA
V _T	on-state voltage	I _T = 12 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.25	1.5	V
Dynamic ch	aracteristics	·				
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T _j = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit	20	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	V_D = 400 V; T _j = 125 °C; I _{T(RMS)} = 10 A; dV _{com} /dt = 20 V/µs; (snubberless condition); gate open circuit	1	-	-	A/ms
		V_D = 400 V; T _j = 125 °C; I _{T(RMS)} = 10 A; dV _{com} /dt = 10 V/µs; gate open circuit	1.5	-	-	A/ms
		V_D = 400 V; T _j = 125 °C; I _{T(RMS)} = 10 A; dV _{com} /dt = 1 V/µs; gate open circuit	4.5	-	-	A/ms

5. Pinning information

Table 2. Pinning information Pin **Simplified outline** Symbol Description **Graphic symbol** 1 T1 main terminal 1 mb T2 T1 T2 2 main terminal 2 G sym051 3 G gate T2 mb mounting base; main terminal 2 2 3 1 **TO-220AB (SOT78)**

6. Ordering information

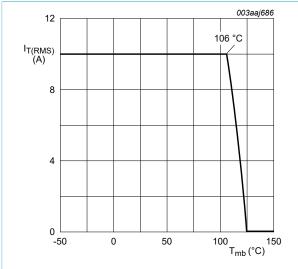
Table 3. Ordering information						
Type number	Package					
	Name	Description	Version			
BTA310-600D	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78			

7. Limiting values

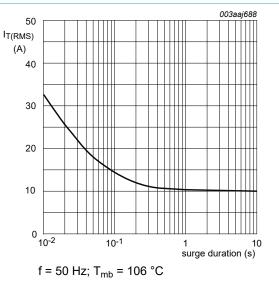
Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DRM}	repetitive peak off-state voltage		-	600	V
I _{T(RMS)}	RMS on-state current	full sine wave; T _{mb} ≤ 106 °C; <u>Fig. 1;</u> Fig. 2; <u>Fig. 3</u>	-	10	A
I _{TSM}	non-repetitive peak on- state current	full sine wave; T _{j(init)} = 25 °C; t _p = 20 ms; <u>Fig. 4; Fig. 5</u>	-	85	A
		full sine wave; T _{j(init)} = 25 °C; t _p = 16.7 ms	-	93	А
l ² t	I ² t for fusing	t _p = 10 ms; SIN	-	36.1	A²s
dl _T /dt	rate of rise of on-state current	I _G = 0.2 A	-	100	A/µs
I _{GM}	peak gate current		-	2	А
P _{GM}	peak gate power		-	5	W
P _{G(AV)}	average gate power	over any 20 ms period	-	0.5	W
T _{stg}	storage temperature		-40	150	°C
T _i	junction temperature		-	125	°C

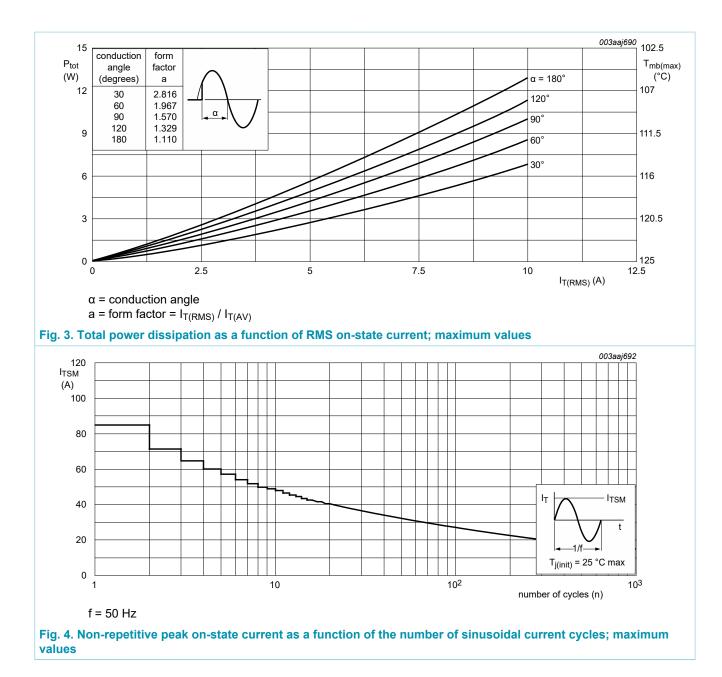






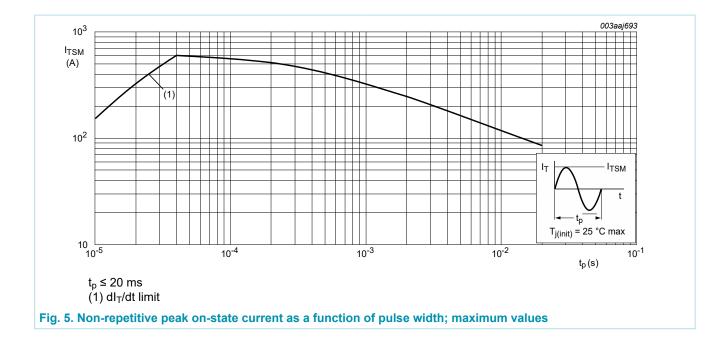


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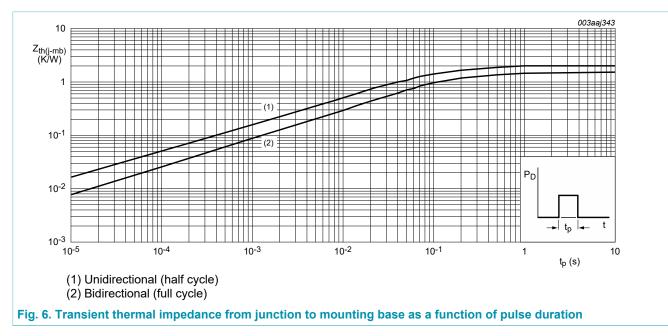
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8. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	full cycle; <u>Fig. 6</u>	-	-	1.5	K/W
		half cycle; <u>Fig. 6</u>	-	-	2	K/W
R _{th(j-a)} thermal resistance from junction to ambient free air		in free air	-	60	-	K/W



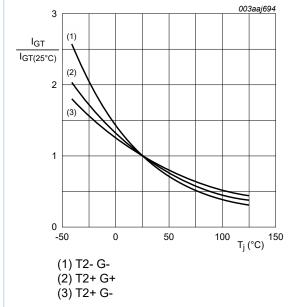
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9. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics					
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 7</u>	0.3	-	5	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 7</u>	0.3	-	5	mA
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 7</u>	0.3	-	5	mA
ΙL	latching current	V _D = 12 V; I _G = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 8</u>	-	-	10	mA
		V _D = 12 V; I _G = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 8</u>	-	-	15	mA
		V _D = 12 V; I _G = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 8</u>	-	-	15	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	10	mA
V _T	on-state voltage	I _T = 12 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.25	1.5	V
V _{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C; <u>Fig. 11</u>	-	0.7	1	V
		V _D = 400 V; I _T = 0.1 A; T _j = 125 °C; <u>Fig. 11</u>	0.25	0.4	-	V
I _D	off-state current	V _D = 600 V; T _j = 125 °C	-	0.1	0.5	mA
Dynamic ch	naracteristics					
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T _j = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit	20	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	$\label{eq:VD} \begin{array}{l} V_D = 400 \text{ V}; \text{T}_j = 125 \ ^\circ\text{C}; \text{I}_{\text{T}(\text{RMS})} = 10 \text{ A}; \\ \text{d} V_{\text{com}}/\text{d} \text{t} = 20 \ \text{V}/\mu\text{s}; (\text{snubberless} \\ \text{condition}); \text{ gate open circuit} \end{array}$	1	-	-	A/ms
		$\label{eq:VD} \begin{array}{l} V_D = 400 \text{ V}; \text{T}_{\text{j}} = 125 ^\circ\text{C}; \text{I}_{\text{T}(\text{RMS})} = 10 \text{ A}; \\ \text{d} V_{\text{com}}/\text{d} t = 10 \text{V}/\mu\text{s}; \text{ gate open circuit} \end{array}$	1.5	-	-	A/ms
		V_D = 400 V; T _j = 125 °C; I _{T(RMS)} = 10 A; dV _{com} /dt = 1 V/µs; gate open circuit	4.5	-	-	A/ms

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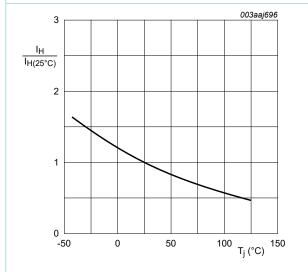
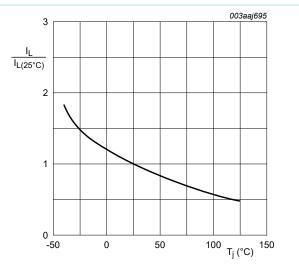
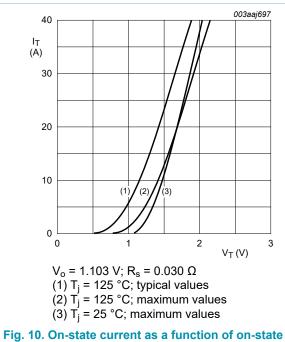


Fig. 9. Normalized holding current as a function of junction temperature



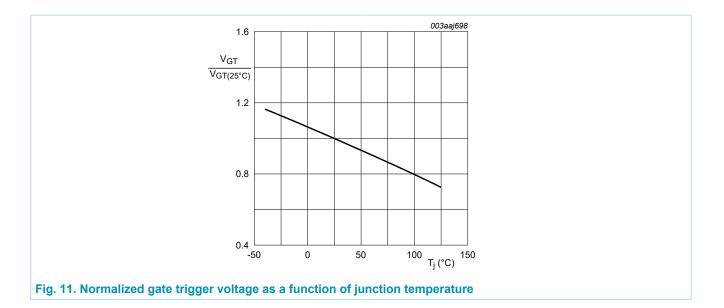




voltage

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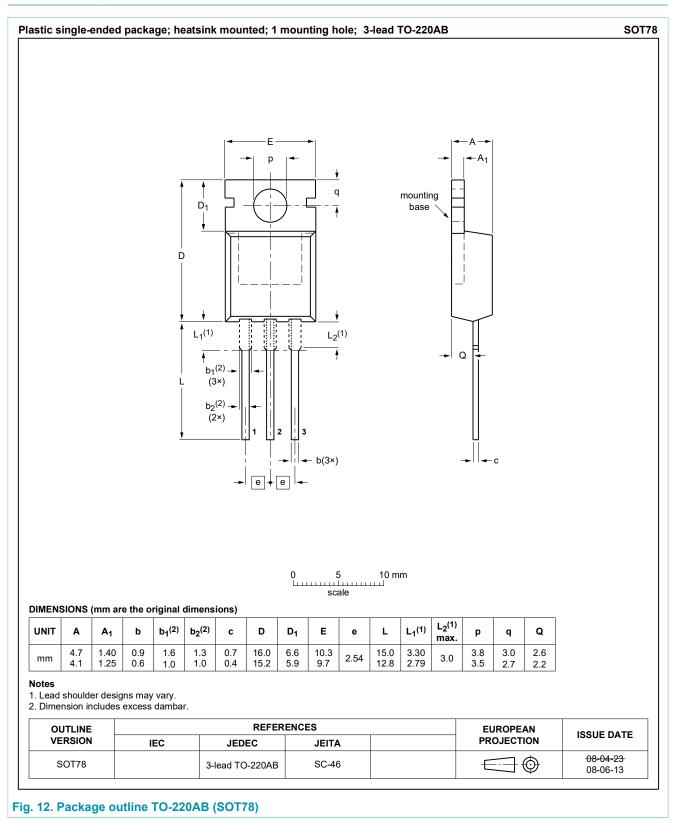
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10. Package outline



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11. Legal information

Data sheet status

Document status [1][2]	Product status [<u>3]</u>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

- [2] The term 'short data sheet' is explained in section "Definitions".
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